

BFG93A; BFG93A/X

NPN 6 GHz wideband transistors

Rev. 05 — 26 November 2007

Product data sheet

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FEATURES

- High power gain
- Low noise figure
- Gold metallization ensures excellent reliability.

APPLICATIONS

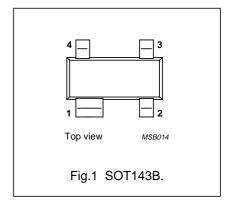
Wideband applications in the UHF and microwave range.

DESCRIPTION

NPN transistor in a 4-pin, dual-emitter SOT143B plastic package.

PINNING

PIN	DESCRIPTION				
BFG93	A				
1	collector				
2	base				
3	emitter				
4	emitter				
BFG93	A/X				
1	collector				
2	emitter				
3	base				
4	emitter				



MARKING

TYPE NUMBER	CODE
BFG93A	R8%
BFG93A/X	%MX

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	_	15	V
V _{CEO}	collector-emitter voltage	open base	_	_	12	V
I _C	collector current (DC)		_	_	35	mA
P _{tot}	total power dissipation	T _s ≤ 85 °C	_	_	300	mW
C _{re}	feedback capacitance	$I_C = i_c = 0$; $V_{CB} = 5 \text{ V}$; $f = 1 \text{ MHz}$	_	0.6	_	pF
f _T	transition frequency	I _C = 30 mA; V _{CE} = 5 V; f = 500 MHz	4.5	6	_	GHz
G _{UM}	maximum unilateral power gain	I_C = 30 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	_	16	_	dB
		I_C = 30 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz	_	10	_	dB
F	noise figure	$\Gamma_{\text{S}} = \Gamma_{\text{opt}}$; $I_{\text{C}} = 5$ mA; $V_{\text{CE}} = 8$ V; $T_{\text{amb}} = 25$ °C; $f = 1$ GHz	_	1.7	_	dB

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	15	V
V_{CEO}	collector-emitter voltage	open base	_	12	V
V _{EBO}	emitter-base voltage	open collector	_	2	V
I _C	collector current (DC)		_	35	mA
P _{tot}	total power dissipation	T _s ≤ 85 °C; note 1	_	300	mW
T _{stg}	storage temperature range		-65	+150	°C
T _j	junction operating temperature		_	175	°C

Note

1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	note 1	290	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICS

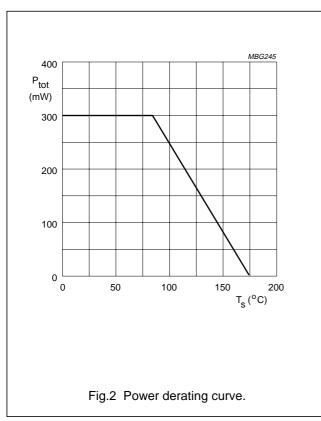
 $T_i = 25$ °C unless otherwise specified.

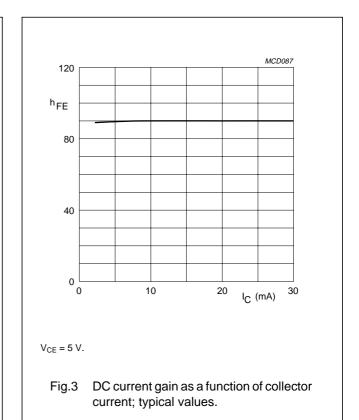
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector leakage current	I _E = 0; V _{CB} = 5 V	_	_	50	nA
h _{FE}	DC current gain	$I_C = 30 \text{ mA}; V_{CE} = 5 \text{ V}$	40	90	_	
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = 5 V; f = 1 MHz$	_	0.9	_	pF
C _e	emitter capacitance	$I_C = i_C = 0$; $V_{EB} = 5 \text{ V}$; $f = 1 \text{ MHz}$	_	1.9	_	pF
C _{re}	feedback capacitance	$I_C = i_c = 0$; $V_{CB} = 5 \text{ V}$; $f = 1 \text{ MHz}$	_	0.6	_	pF
f _T	transition frequency	$I_C = 30 \text{ mA}; V_{CE} = 5 \text{ V}; f = 500 \text{ MHz}$	4.5	6	_	GHz
G _{UM}	maximum unilateral power gain; note 1	I_C = 30 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 1 GHz	_	16	_	dB
		I_C = 30 mA; V_{CE} = 8 V; T_{amb} = 25 °C; f = 2 GHz	_	10	_	dB
F	noise figure	$\Gamma_{\text{S}} = \Gamma_{\text{opt}}; I_{\text{C}} = 5 \text{ mA}; V_{\text{CE}} = 8 \text{ V};$ $T_{\text{amb}} = 25 ^{\circ}\text{C}; f = 1 \text{ GHz}$	_	1.7	_	dB
		$\begin{split} \Gamma_{\text{S}} &= \Gamma_{\text{opt}}; \ I_{\text{C}} = 5 \ \text{mA}; \ V_{\text{CE}} = 8 \ \text{V}; \\ T_{\text{amb}} &= 25 \ ^{\circ}\text{C}; \ \text{f} = 2 \ \text{GHz} \end{split}$	_	2.3	_	dB

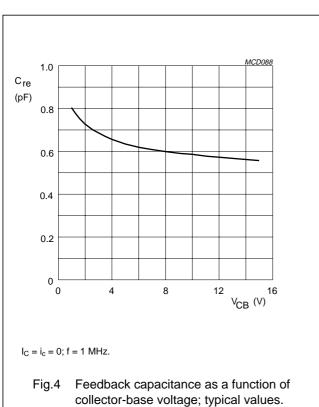
Note

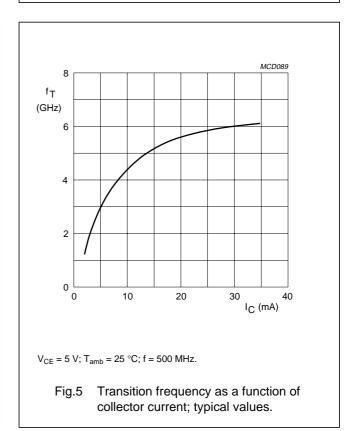
1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)}$ dB.

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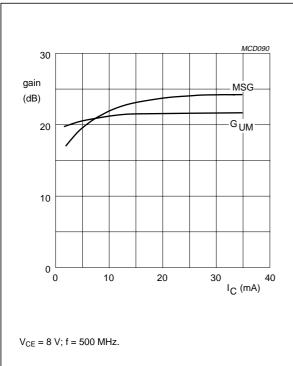
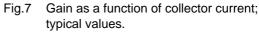
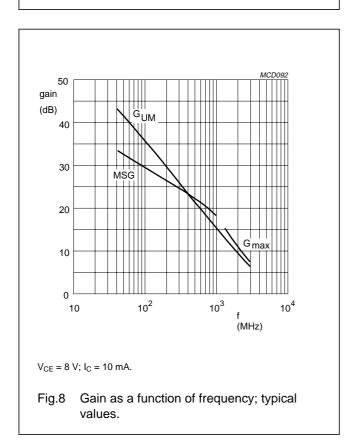
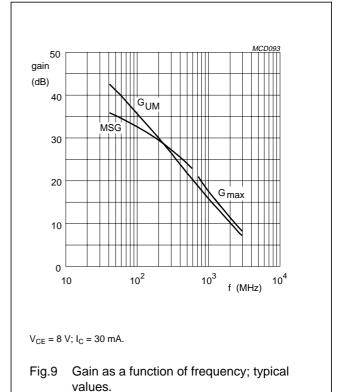


Fig.6 Gain as a function of collector current; typical values.







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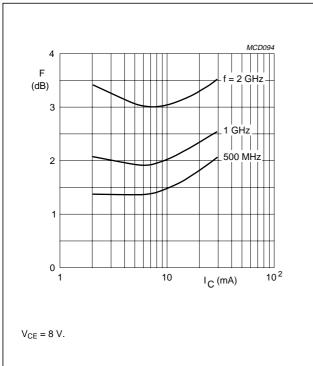
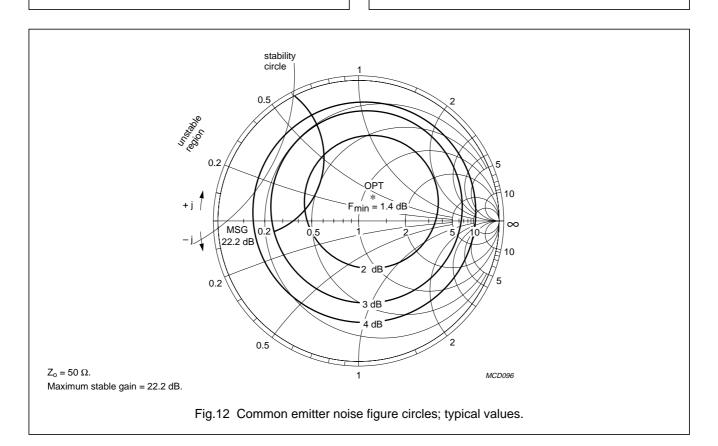


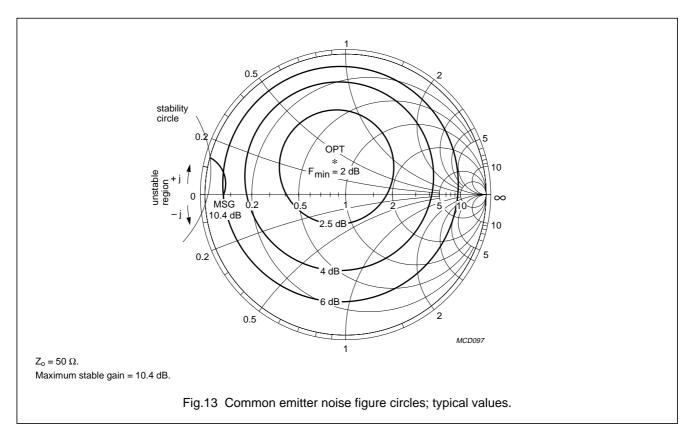
Fig.11 Minimum noise figure as a function of $\frac{A}{F}$ (dB) \frac{A}

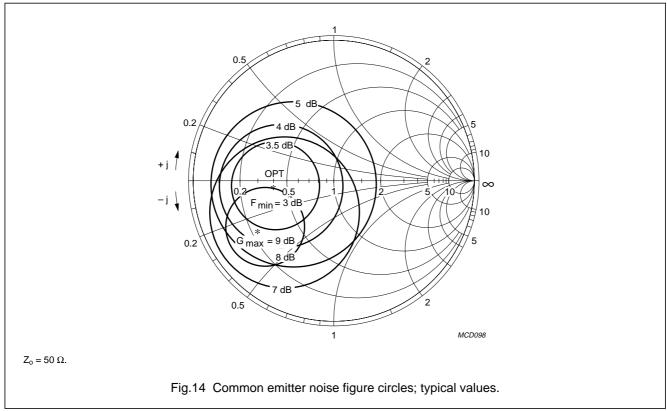
frequency; typical values.

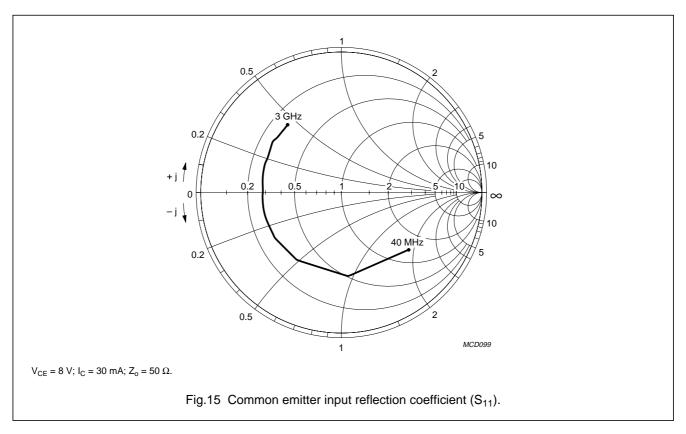
Fig.10 Minimum noise figure as a function of collector current; typical values.

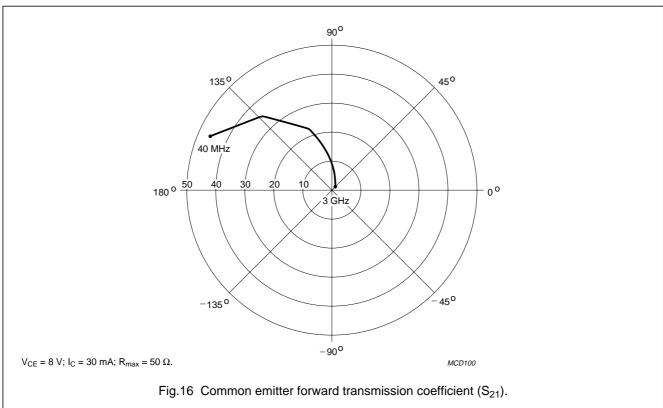


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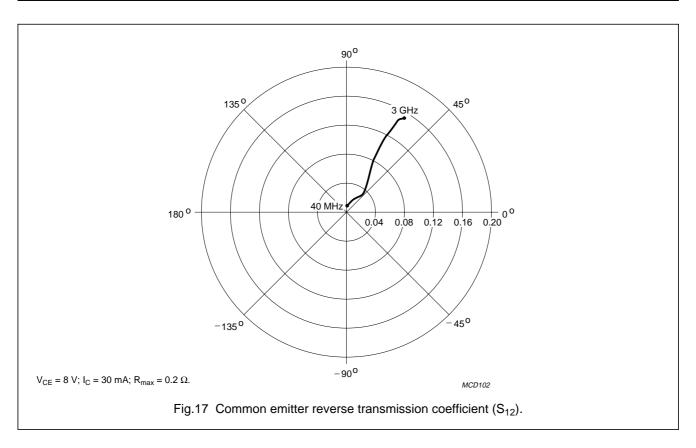


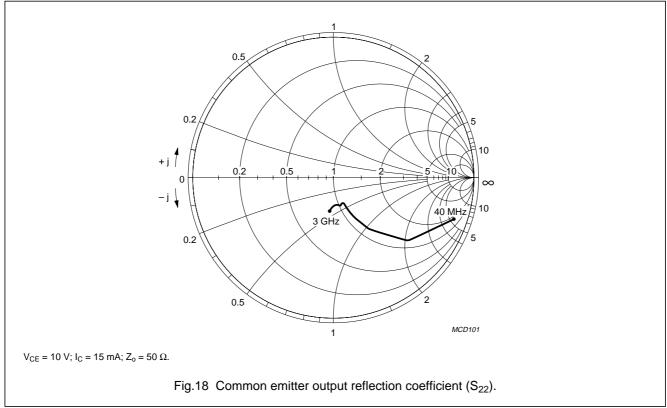






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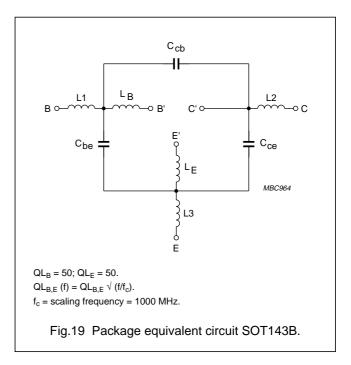
SPICE parameters for BFR91A(/X) die

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	1.328	fA
2	BF	102.0	_
3	NF	1.000	_
4	VAF	51.90	V
5	IKF	8.155	Α
6	ISE	13.90	fA
7	NE	15.12	_
8	BR	17.69	_
9	NR	994.0	m
10	VAR	3.280	V
11	IKR	10.00	Α
12	ISC	1.043	аА
13	NC	1.189	_
14	RB	10.00	Ω
15	IRB	1.000	μΑ
16	RBM	10.00	Ω
17	RE	763.6	mΩ
18	RC	9.000	Ω
19 (note 1)	XTB	0.000	_
20 (note 1)	EG	1.110	EV
21 (note 1)	XTI	3.000	_
22	CJE	2.032	pF
23	VJE	600.0	mV
24	MJE	290.0	m
25	TF	6.557	ps
26	XTF	38.97	_
27	VTF	10.93	V
28	ITF	521.0	mA
29	PTF	0.000	deg
30	CJC	1.003	pF
31	VJC	340.8	mV
32	MJC	194.2	m
33	XCJC	120.0	m
34	TR	3.073	ns
35 (note 1)	CJS	0.000	F

SEQUENCE No. PARAMETER		VALUE	UNIT
36 (note 1)	VJS	750.0	mV
37 (note 1)	MJS	0.000	-
38	FC	800.0	m

Note

1. These parameters have not been extracted, the default values are shown.



List of components (see Fig.19)

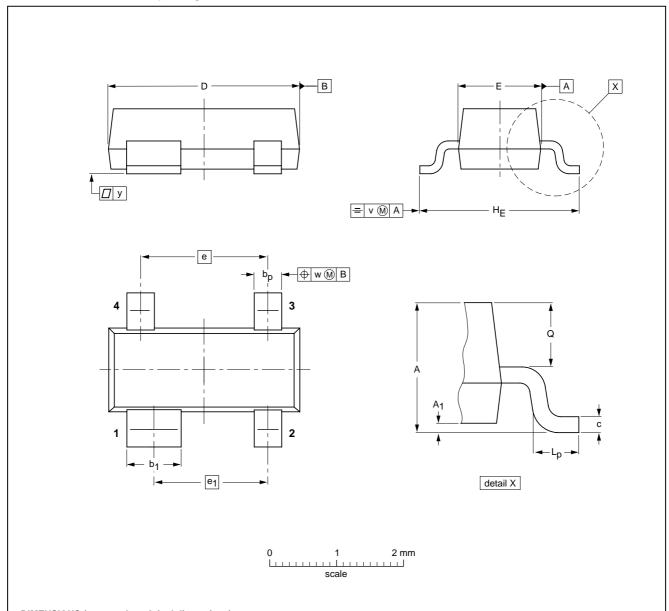
DESIGNATION	VALUE	UNIT
C _{be}	84	fF
C _{cb}	17	fF
C _{ce}	191	fF
L1	0.12	nH
L2	0.21	nH
L3	0.06	nH
L _B	0.95	nH
L _E	0.40	nH

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PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

SOT143B



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	bp	b ₁	С	D	E	е	e ₁	HE	L _p	Q	v	w	у
mm	1.1 0.9	0.1	0.48 0.38	0.88 0.78	0.15 0.09	3.0 2.8	1.4 1.2	1.9	1.7	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1	0.1

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT143B						97-02-28

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Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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Revision history

Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFG93A_X_N_5	20071126	Product data sheet	-	BFG93A_X_4
Modifications:	 Marking table 	e on page 2; changed code		
BFG93A_X_4 (9397 750 04351)	19980923	Product specification	-	BFG93SERIES_3
BFG93SERIES_3	19950925	Product specification	-	BFG93SERIES_2
BFG93SERIES_2	-	Product specification	-	BFG93_SERIES_1
BFG93_SERIES_1	-	-	-	-

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